

SOT1390-12

WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

14 October 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP12
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	S (silicon)
Mounting method type	S (surface mount)
Issue date	04-07-2022
Manufacturer package code	98ASA01954D

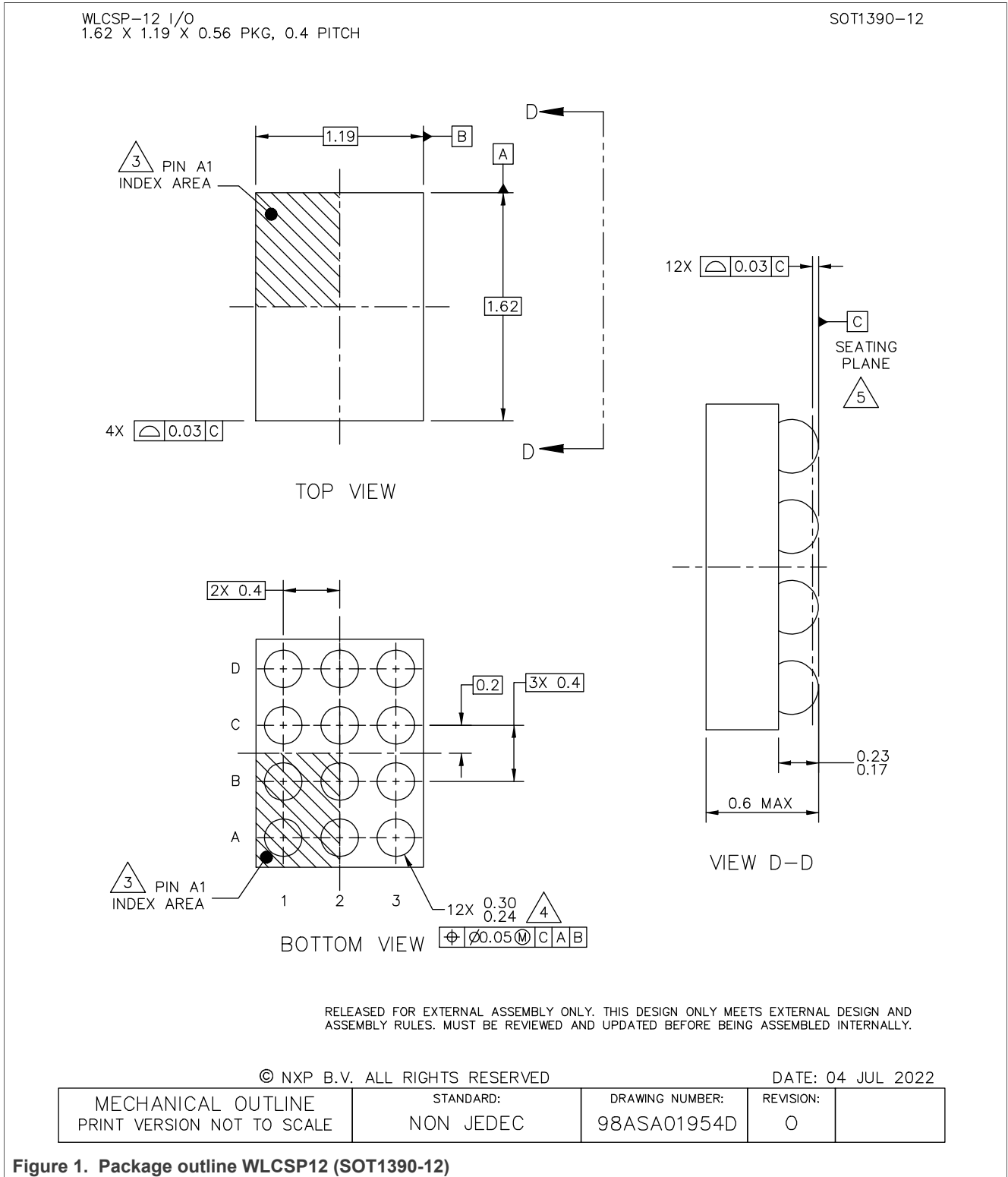
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.59	1.62	1.65	
package width	1.16	1.19	1.22	
seated height	-	0.56	0.6	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	12	-	



WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

2 Package outline

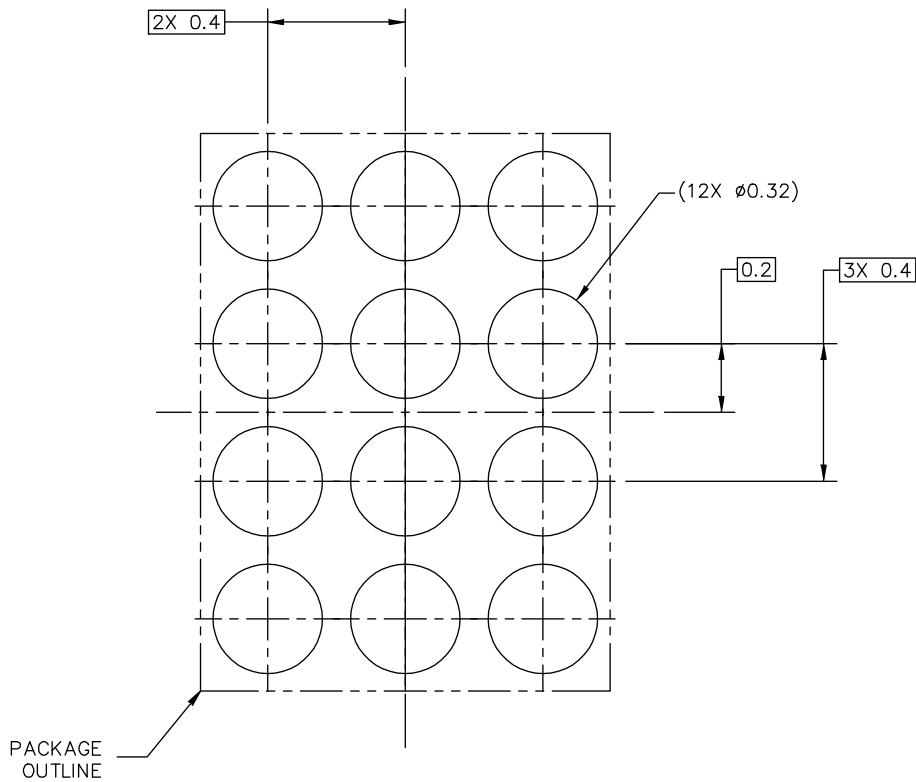


WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

3 Soldering

WLCSP-12 I/O
1.62 X 1.19 X 0.56 PKG, 0.4 PITCH

SOT1390-12



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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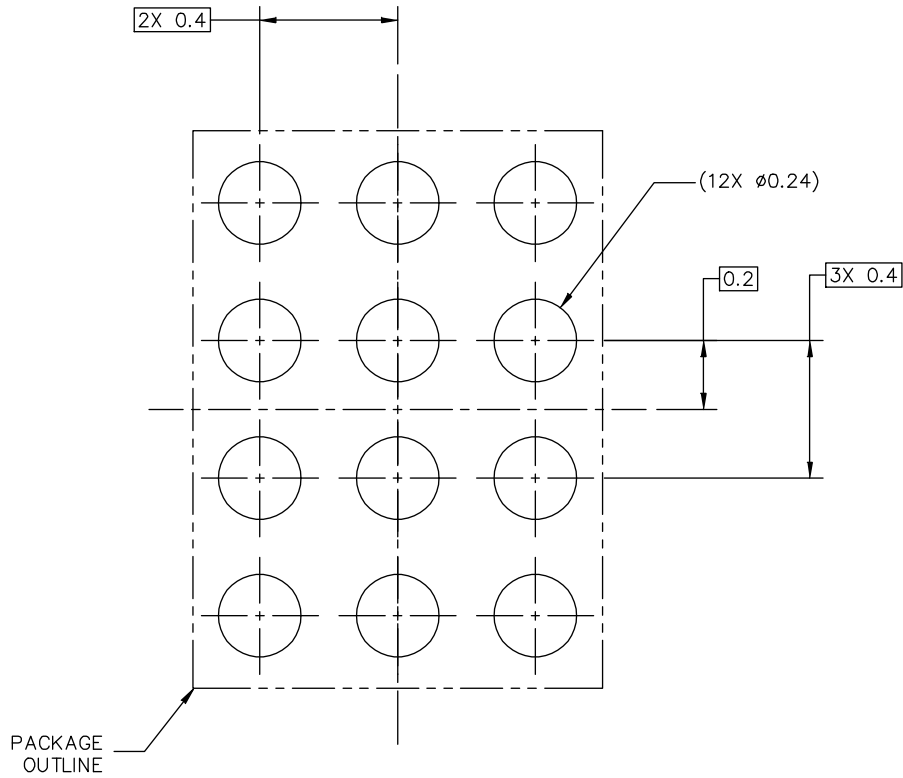
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01954D	REVISION: 0	
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Figure 2. Reflow soldering footprint part1 for WLCSP12 (SOT1390-12)

WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

WLCSP-12 I/O
1.62 X 1.19 X 0.56 PKG, 0.4 PITCH

SOT1390-12



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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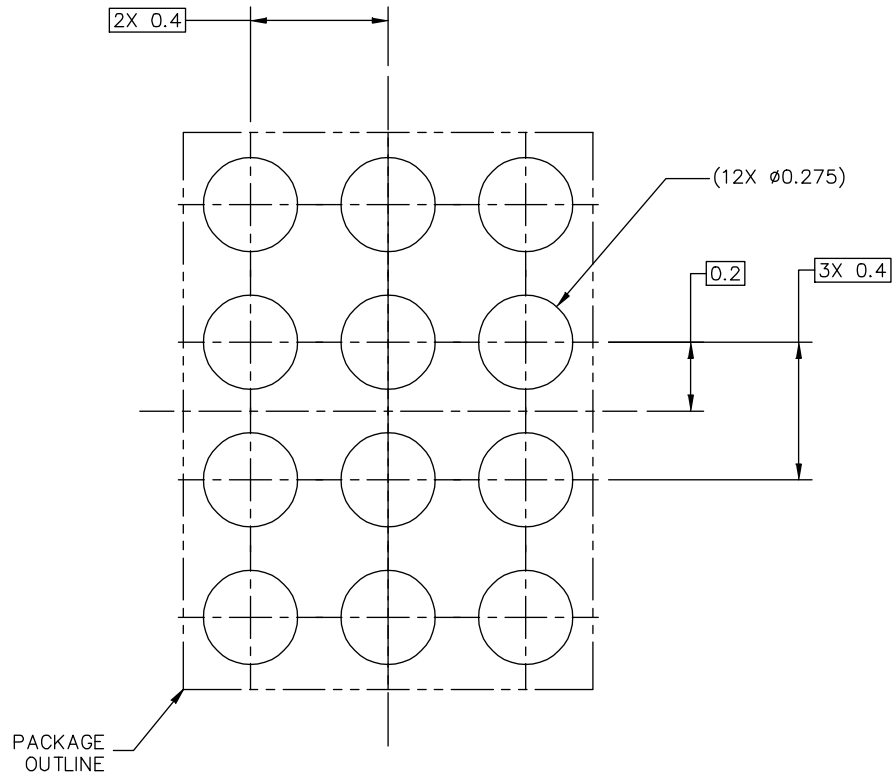
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01954D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for WLCSP12 (SOT1390-12)

WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

WLCSP-12 I/O
1.62 X 1.19 X 0.56 PKG, 0.4 PITCH

SOT1390-12



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for WLCSP12 (SOT1390-12)

WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

WLCSP-12 I/O
1.62 X 1.19 X 0.56 PKG, 0.4 PITCH

SOT1390-12

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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Figure 5. Package outline note WLCSP12 (SOT1390-12)

4 Legal information

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WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm
body

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